



**IEEE International Mediterranean Conference  
on Communications and Networking**  
5–8 September 2022 // Athens, Greece

**Workshop on  
Intelligent Distribution of Computing in Cloud Continuum  
(ID3C)**

<b>Organizing Projects</b>	<ul style="list-style-type: none"><li>• CONNECT (<a href="https://connect.ku.edu.tr/">https://connect.ku.edu.tr/</a>)</li><li>• DiPET (<a href="https://dipet.eecs.qub.ac.uk/">https://dipet.eecs.qub.ac.uk/</a>)</li><li>• DRUID-NET (<a href="https://druidnet.netmode.ntua.gr/">https://druidnet.netmode.ntua.gr/</a>)</li><li>• LeadingEdge (<a href="https://mm.aueb.gr/leadingedge/">https://mm.aueb.gr/leadingedge/</a>)</li><li>• SCORING (<a href="https://www.chistera.eu/projects/scoring">https://www.chistera.eu/projects/scoring</a>)</li></ul>
<b>Structure</b>	Full Day
<b>Organizers</b>	<ul style="list-style-type: none"><li>• <b>Symeon Papavassiliou</b>, NTUA, Greece, <a href="mailto:papavass@mail.ntua.gr">papavass@mail.ntua.gr</a></li><li>• <b>Dimitrios Dechouniotis</b>, NTUA, Greece, <a href="mailto:ddechou@netmode.ntua.gr">ddechou@netmode.ntua.gr</a></li><li>• <b>Yacine Ghamri-Doudane</b>, La Rochelle University, France <a href="mailto:yacine.ghamri@univ-lr.fr">yacine.ghamri@univ-lr.fr</a></li><li>• <b>Sinem Coleri</b>, Koc University, Turkey, <a href="mailto:scoleri@ku.edu.tr">scoleri@ku.edu.tr</a></li><li>• <b>Iordanis Koutsopoulos</b>, AUEB, Greece, <a href="mailto:jordan@aeub.gr">jordan@aeub.gr</a></li><li>• <b>Hans Vandierendonck</b>, QUB, Northern Ireland <a href="mailto:h.vandierendonck@qub.ac.uk">h.vandierendonck@qub.ac.uk</a></li></ul>
<b>Publicity Chair</b>	<ul style="list-style-type: none"><li>• <b>Eirini Eleni Tsiropoulou</b>, University of New Mexico, USA, <a href="mailto:eirini@unm.edu">eirini@unm.edu</a></li></ul>

## Background and Motivation

The proliferation of IoT solutions is driving the development of novel computing platforms that cope with the limitations of sensor/actuation devices and mobile devices, by offloading computing complexity onto the network. As a result, new computing paradigms that support diverse applications' needs have arisen including cloud, fog and edge computing. Increasingly hybrid approaches are being adopted to provide performance trade-offs among those distribution models according to changing network conditions and application requirements. This trend is foreseen to continue to grow especially in smart environments powered by post-5G networks. Processing will have to be delegated via novel intelligent coordination strategies over dynamic networks, including cloud, fog and edge elements. There is a need for ubiquitous, context-aware, robust solutions that dynamically orchestrate computing tasks among these models.

## Topics of Interest

ID3C 2022 has the goal to meet together researchers and practitioners from academia and industry that are actively involved in computing of dynamic networks related research projects.

The topics of interest for ID3C 2022 include, but are not limited to:

- Resource scheduling in Cloud Continuum
- Artificial Intelligence for Cloud Continuum
- Computation Co-design in Cloud Continuum
- Energy-aware Computing at the network edge
- SDN/NFV-based solutions for Cloud Continuum
- Network Architectures and Models for Cloud Continuum
- Distribution of Computing in Cyber-Physical Systems
- Task Offloading in Cloud Continuum
- Smart Distribution of Computing for IoT Networks
- Smart Distribution of Computing for Sensors Networks
- Smart Distribution of Computing for Vehicular Networks
- Smart Distribution of Computing for Smart Grids
- Control Theory for Cloud Continuum
- Data Analytics for Smart Computing Distribution
- Artificial Intelligence and Computing Distribution
- Machine learning for Intelligent Distribution of Computing
- Workload and Application Modeling
- Novel Network Architectures

# Workshop Proposals Timeline

Paper Submission Deadline: **8 July 2022**

Paper Acceptance Notification: **31 July 2022**

Camera Ready: **10 August 2022**

## Submission Guidelines

Please use the Standard IEEE conference templates for LaTeX formats, which are found [here](#). You may also use one of the following templates for Microsoft Word: A4, US letter. Only PDF files will be accepted for the review process, and all submissions must be done through [EDAS](#).

Papers should not include material already published or submitted for publication to any other conference at the same time. More information can be found at:

- [IEEE Policy on Plagiarism](#)
- [IEEE Policy on Double Submission](#)

A submitted paper that is accepted for publication will be eligible for publication in the IEEE MeditCom 2022 Conference Proceedings and the IEEE Xplore (or an extended abstract for publication in the Conference Proceedings), only if one of the paper authors registers to the relevant Workshop / Special Session and the paper is presented by an author of that paper. In situations where the presentation cannot be performed by one of the authors of the paper, a substitute presenter qualified both to present and answer questions can give the presentation instead. However, this required a permission granted by the Workshop Organizers in advance of the event. Non-refundable registration fees must be paid prior to uploading the final IEEE formatted, publication-ready version of the paper or the extended abstract.

The page length limit for initial submission for review is SIX (6) printed pages (10-point font) and must be written in English. Initial submissions longer than SIX (6) pages will be rejected without review. Final submissions of accepted papers must be written in English with a maximum paper length of SIX (6) printed pages (10-point font) including figures. No more than one (1) additional printed page (10-point font) may be included in final submissions and the extra page (the 7th page) will incur an over length page charge of US\$100.

All final papers must be submitted to the IEEE Conference eXpress website. Please refer to the acceptance letter for the instructions on how to upload final papers.

If you have any questions regarding the submission of manuscripts, please contact one of the Workshop Organizers.